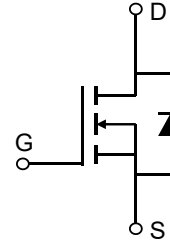


Description

Features

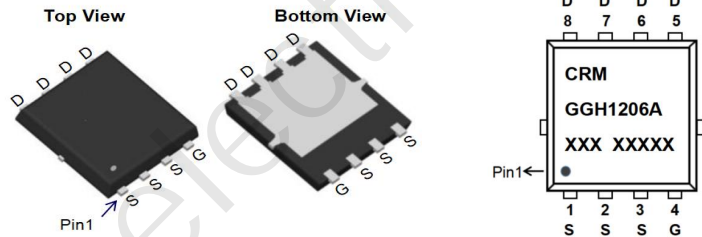
- 120V, 90A
 $R_{DS(ON)}$ Typ = 6.5mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

| Device | Marking | Package | Outline | Reel Size | Reel (pcs) | Per Carton (pcs) |
|-------------|-------------|------------|---------|-----------|------------|------------------|
| CRMGGH1206A | CRMGGH1206A | PDFN5x6-8L | TAPING | 13" | 5000 | 50000 |

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

| Symbol | Parameter | Value | Units |
|-----------------|---|---------------------|-------|
| V_{DS} | Drain-to-Source Voltage | 120 | V |
| V_{GS} | Gate-to-Source Voltage | ±20 | V |
| I_D | Continuous Drain Current | $T_C = 25^\circ C$ | 90 |
| | | $T_C = 100^\circ C$ | 54 |
| I_{DM} | Pulsed Drain Current ⁽¹⁾ | 360 | A |
| E_{AS} | Single Pulsed Avalanche Energy ⁽²⁾ | 225 | mJ |
| P_D | Power Dissipation | $T_C = 25^\circ C$ | 125 |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 1 | °C/W |
| T_J, T_{STG} | Junction & Storage Temperature Range | -55 to 150 | °C |

Electrical Characteristics (T_J = 25°C unless otherwise specified)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|--|---|------|------|------|------|
| Off Characteristics | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | I _D = 250μA, V _{GS} = 0V | 120 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 120V, V _{GS} = 0V | - | - | 1.0 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250μA | 2.4 | 3 | 3.6 | V |
| R _{DS(ON)} | Static Drain-Source ON-Resistance ⁽³⁾ | V _{GS} = 10V, I _D = 30A | - | 6.5 | 8.5 | mΩ |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} = 0V, V _{DS} = 60V, f = 1MHz | - | 2712 | - | pF |
| C _{oss} | Output Capacitance | | - | 815 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 7 | - | pF |
| Q _g | Total Gate Charge | V _{GS} = 0 to 10V V _{DS} = 60V, I _D = 20A | - | 33 | - | nC |
| Q _{gs} | Gate Source Charge | | - | 7 | - | nC |
| Q _{gd} | Gate Drain("Miller") Charge | | - | 8 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-On DelayTime | V _{GS} = 10V, V _{DD} = 60V I _D = 20A, R _{GEN} = 6Ω | - | 11 | - | ns |
| t _r | Turn-On Rise Time | | - | 20 | - | ns |
| t _{d(off)} | Turn-Off DelayTime | | - | 32 | - | ns |
| t _f | Turn-Off Fall Time | | - | 28 | - | ns |
| Drain-Source Diode Characteristics and Max Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 90 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 360 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} = 0V, I _S = 30A | - | - | 1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | I _F = 15A, di/dt = 100A/us | - | 54 | - | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | | - | 58 | - | nC |

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DS}=60V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=30A
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit

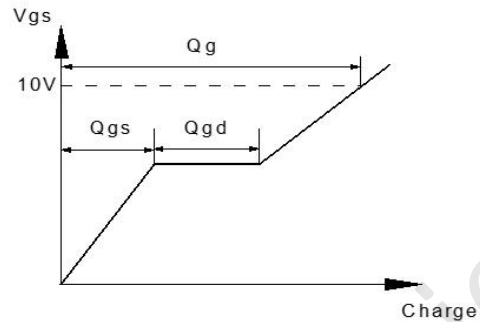
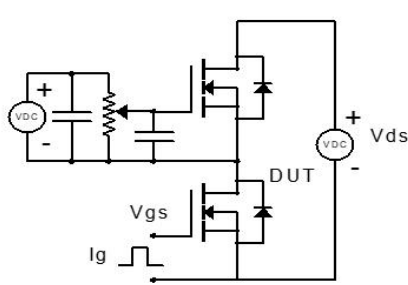


Figure 1: Gate Charge Test Circuit & Waveform

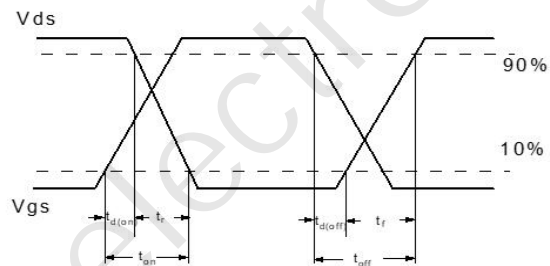
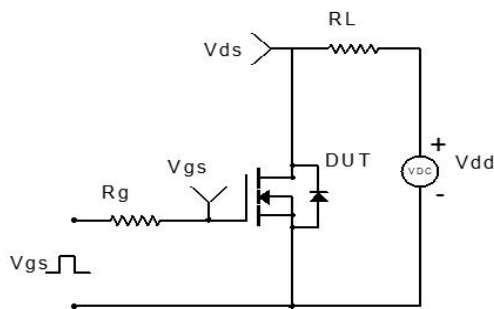


Figure 2: Resistive Switching Test Circuit & Waveform

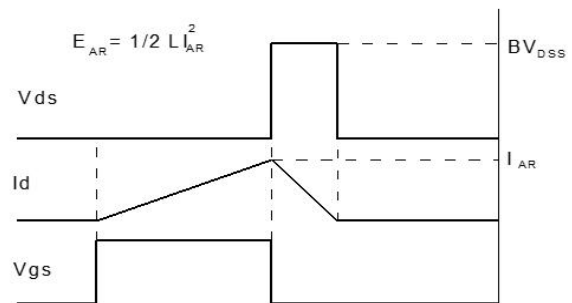
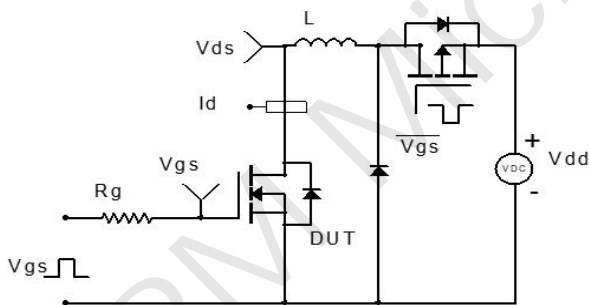


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

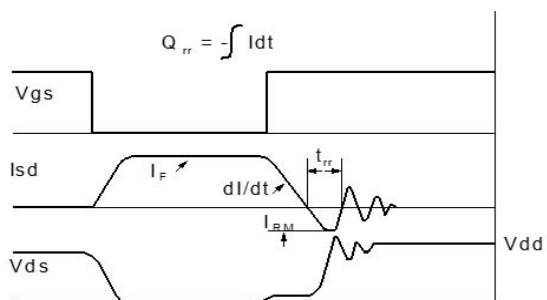
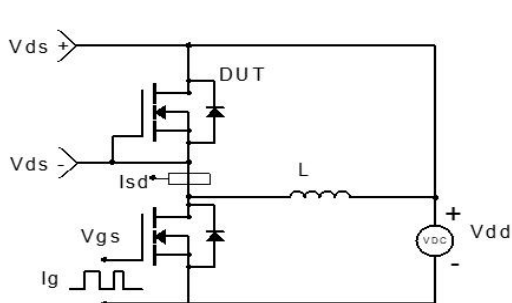
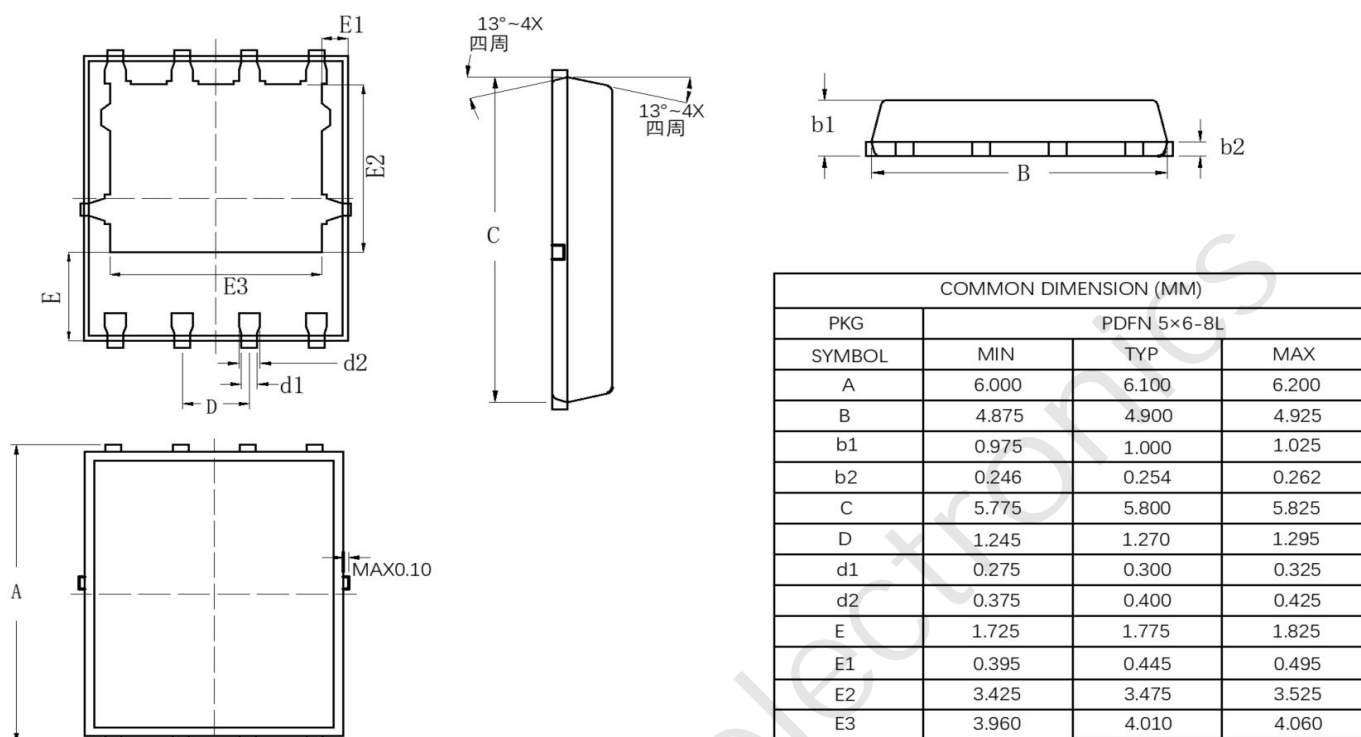


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)




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